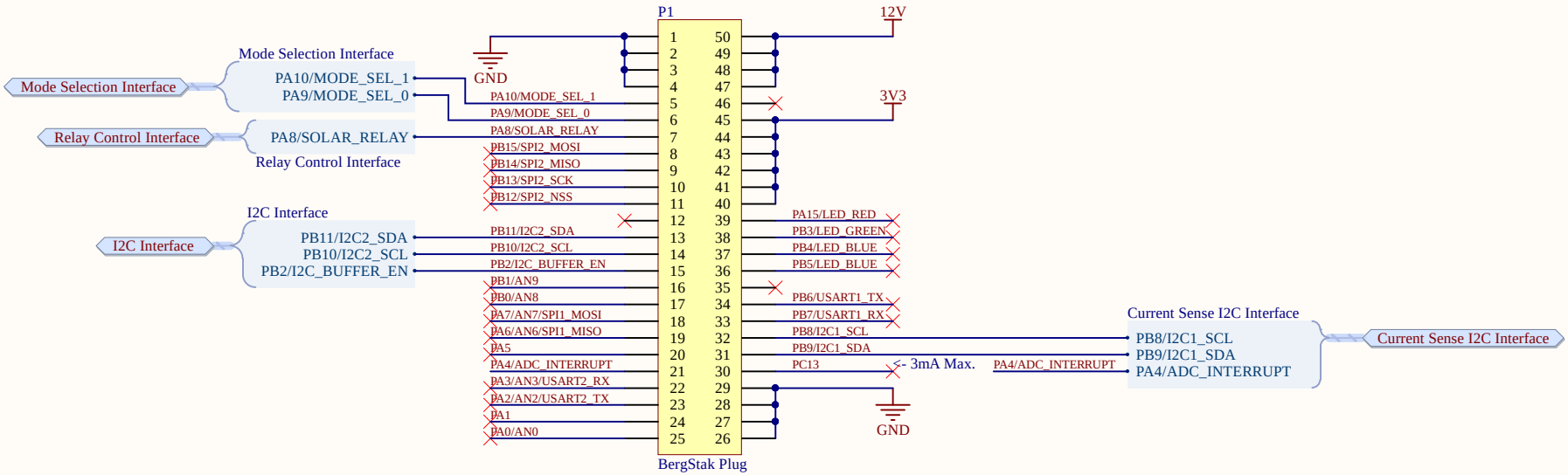
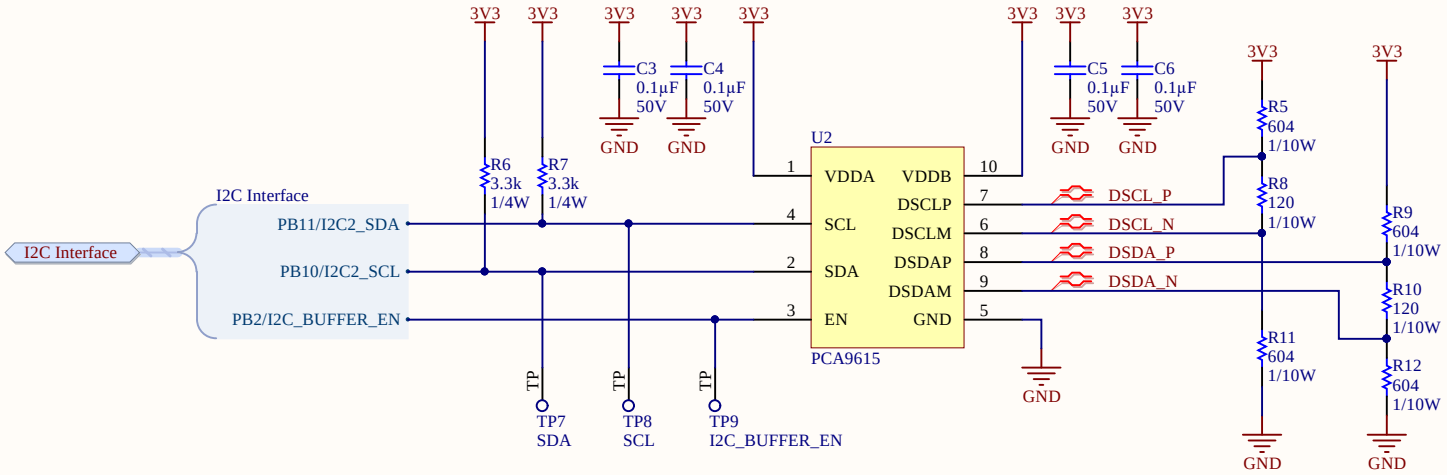
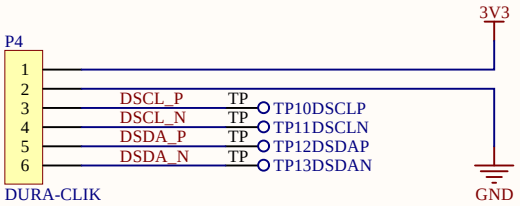
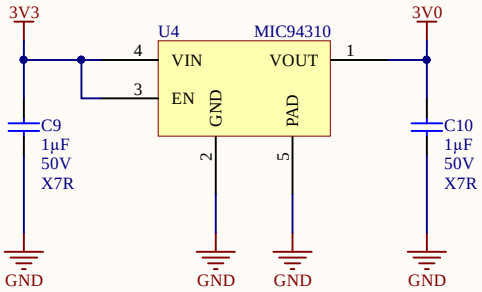


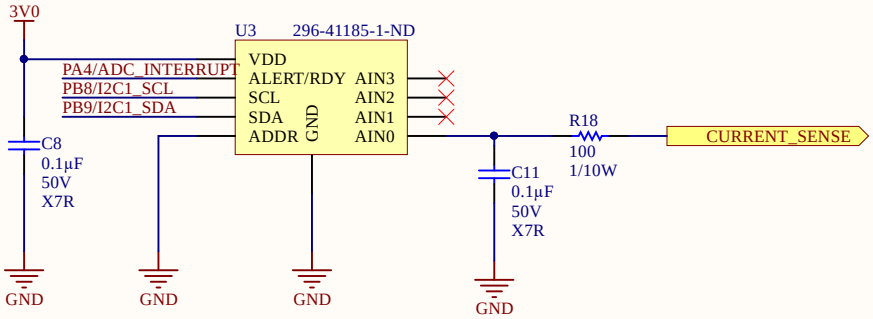
Project: ***MSXII_SolarSenseMaster.PrjPcb***		MIDNIGHT SUN
Title: *		
Project Author: Peiliang Guo		University of Waterloo 200 University Ave W Waterloo, ON, Canada N2L 3E9
Size: Letter	Revision: 1.0	
Date: 2018-07-08	Sheet * of *	Website: www.uwmidsun.com

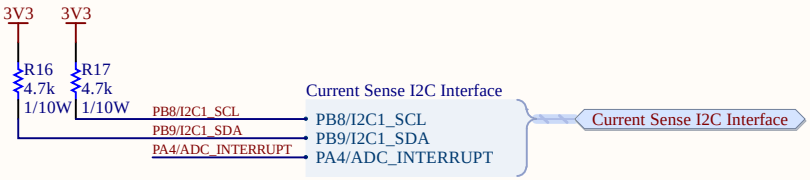
I2C Interface











Project: ***MSXII_SolarSenseMaster.PrjPcb***		MIDNIGHT SUN
Title: *		University of Waterloo 200 University Ave W Waterloo, ON, Canada N2L 3E9
Project Author: Peiliang Guo		
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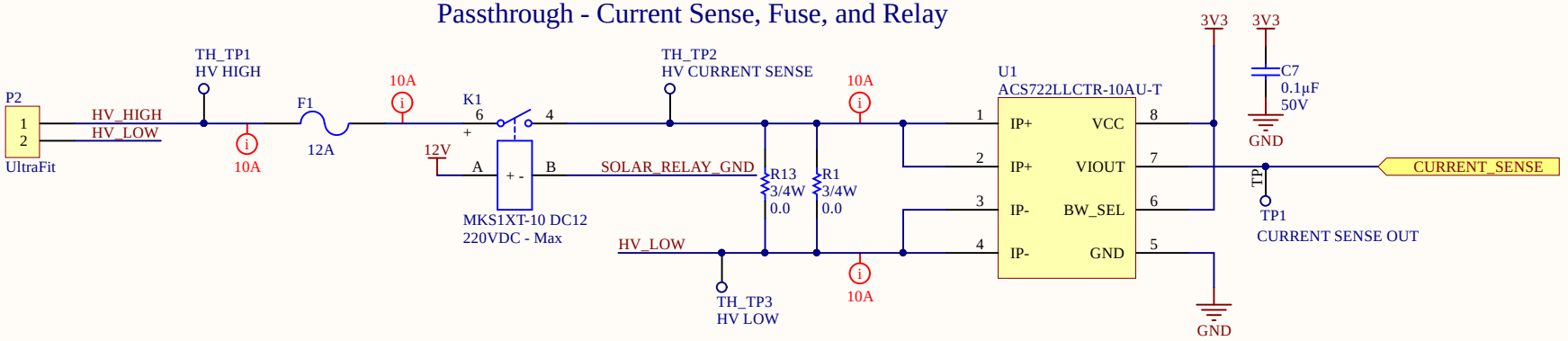
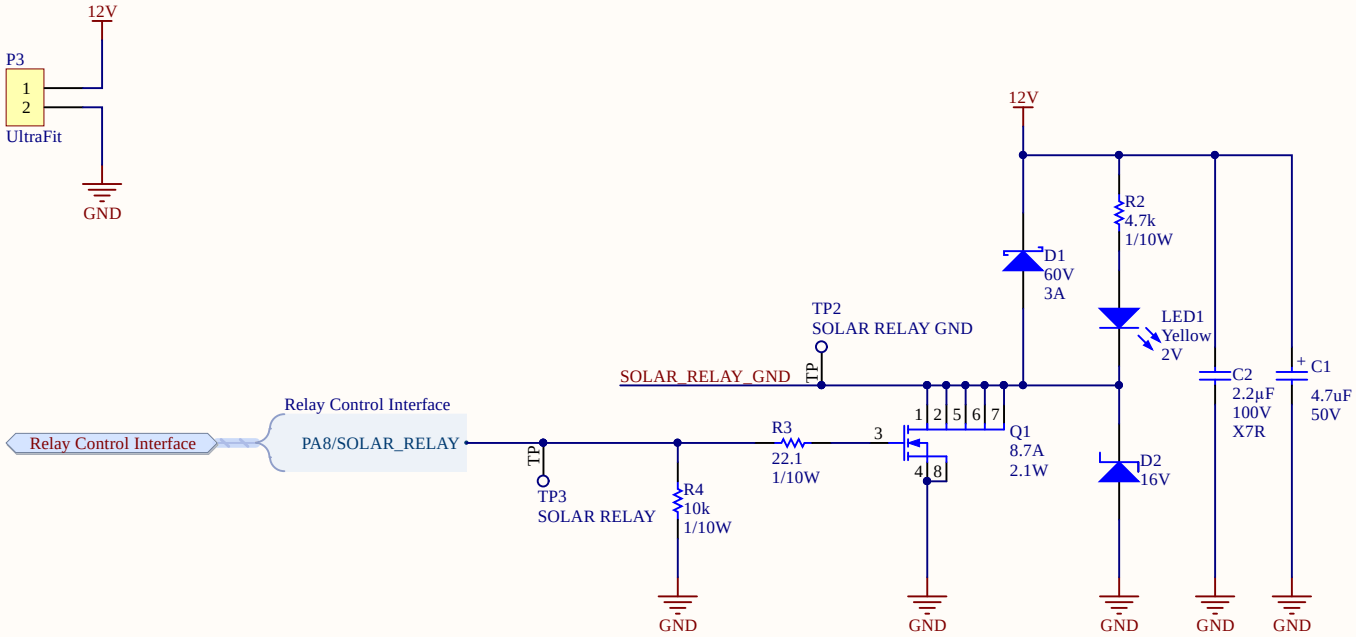
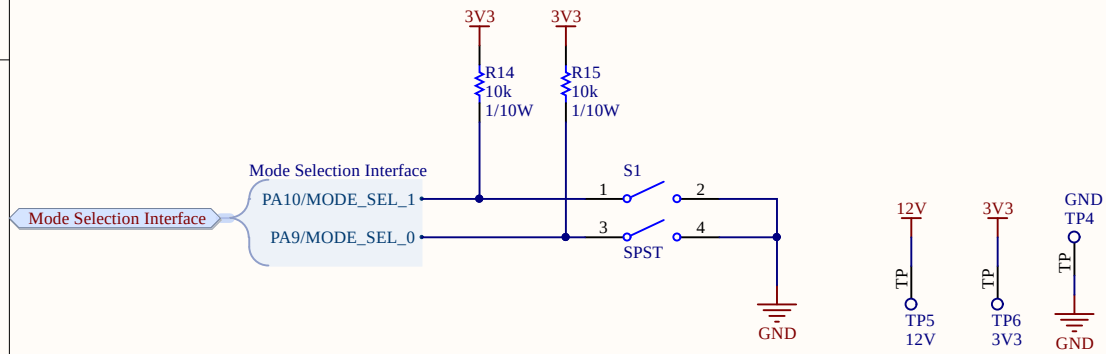
Passthrough - Current Sense, Fuse, and Relay





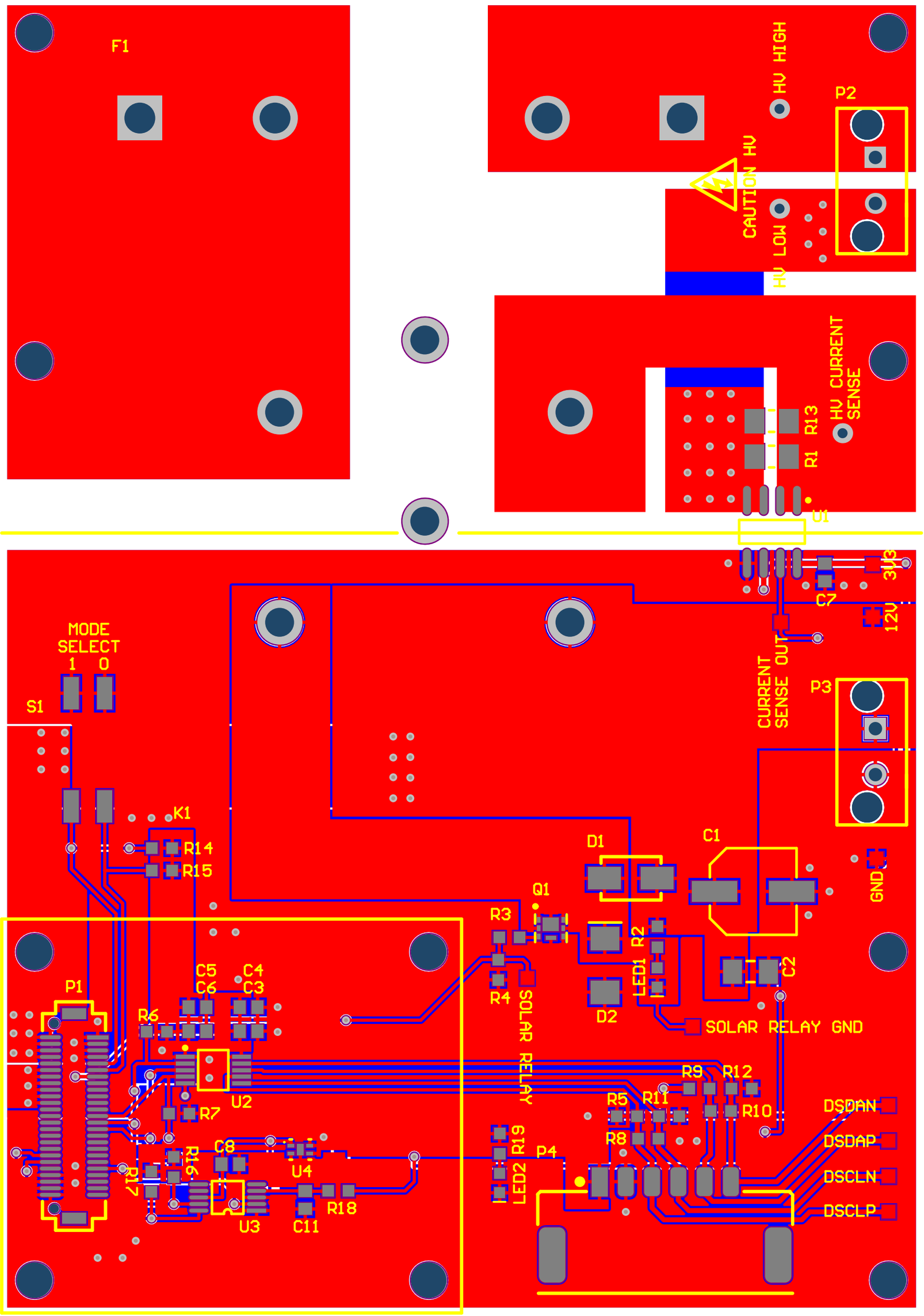


Project: *MSXII_SolarSenseMaster.PrjPcb*		MIDNIGHT SUN
Title: *		University of Waterloo 200 University Ave W Waterloo, ON, Canada N2L 3E9
Project Author: Peiliang Guo		
Size: Letter	Revision: 1.0	
Date: 2018-07-08	Sheet* of *	Website: www.uwmidsun.com

Bill of Materials

Project:	MSXII_SolarSenseMaster.PrjPcb
Revision:	1.0
Project Lead:	Peiliang Guo
Generated On:	2018-07-08 6:36:43 PM
Production Quantity:	1
Currency	CAD
Total Parts Count:	49

LibRef	Designator	Manufacturer 1	Manufacturer Part Number 1	Supplier 1	Supplier Part Number 1	Supplier Unit Price 1	Supplier Order Qty 1	Supplier Subtotal 1
CAP ALUM 4.7UF 20% 50V SMD	C1	Panasonic	EEE-1HA4R7NP	Digi-Key	PCE4304CT-ND	0.56	1	$ 0.56
CAP CER 2.2UF 100V ±20% X7R 1206	C2	Murata	GRM31CR72A225MA73L	Digi-Key	490-12773-1-ND	0.92	1	$ 0.92
CAP CER 0.1UF 50V 10% X7R 0603	C3	Kyocera AVX	06035C-104KAT2A	Digi-Key	478-5052-1-ND	0.21	1	$ 0.21
CAP CER 0.1UF 50V 10% X7R 0603	C4	Kyocera AVX	06035C-104KAT2A	Digi-Key	478-5052-1-ND	0.21	1	$ 0.21
CAP CER 0.1UF 50V 10% X7R 0603	C5	Kyocera AVX	06035C-104KAT2A	Digi-Key	478-5052-1-ND	0.21	1	$ 0.21
CAP CER 0.1UF 50V 10% X7R 0603	C6	Kyocera AVX	06035C-104KAT2A	Digi-Key	478-5052-1-ND	0.21	1	$ 0.21
CAP CER 0.1UF 50V 10% X7R 0603	C7	Kyocera AVX	06035C-104KAT2A	Digi-Key	478-5052-1-ND	0.21	1	$ 0.21
CAP CER 0.1UF 50V 10% X7R 0603	C8	Kyocera AVX	06035C-104KAT2A	Digi-Key	478-5052-1-ND	0.21	1	$ 0.21
CAP CER 1UF 50V 10% X7R 0603	C9	Taiyo Yuden	UMK107AB7105KA-T	Digi-Key	587-3247-1-ND	0.38	1	$ 0.38
CAP CER 1UF 50V 10% X7R 0603	C10	Taiyo Yuden	UMK107AB7105KA-T	Digi-Key	587-3247-1-ND	0.38	1	$ 0.38
CAP CER 0.1UF 50V 10% X7R 0603	C11	Kyocera AVX	06035C-104KAT2A	Digi-Key	478-5052-1-ND	0.21	1	$ 0.21
DIODE SCHOTTKY 60V 3A SMA	D1	Diodes	B360A-13-F	Digi-Key	B360A-FDICT-ND	0.63	1	$ 0.63
DIODE ZENER 16V 5W DO-214AA (SMB)	D2	MCC	SMBJ5353B-TP	Digi-Key	SMBJ5353B-TPMSCT-ND	0.89	1	$ 0.89
FUSE 12 A 600VAC/DC KLM-12	F1	Eaton Bussmann	KLM-12	Digi-Key	KLM-12-ND			
RELAY SPST 12V 10A	K1	Omron	MKS1XT-10DC12	Digi-Key	Z2956-ND	42.55	1	$ 42.55
LED YELLOW CLEAR 2.1V 0603	LED1	Wurth Electronics	150060YS75000	Digi-Key	732-4981-1-ND	0.21	1	$ 0.21
LED GREEN CLEAR 2V 0603	LED2	Wurth Electronics	150060VS75000	Digi-Key	732-4980-1-ND	0.21	1	$ 0.21
CONN 50POS Bergstak Plug 0.02"	P1	Amphenol FCI	10132797-055100LF	Digi-Key	609-5226-1-ND	2.08	1	$ 2.08
CONN 2POS ULTRA-FIT 0.138"	P2	Molex	1722861302	Digi-Key	WM11673-ND	1.81	1	$ 1.81
CONN 2POS ULTRA-FIT 0.138"	P3	Molex	1722861302	Digi-Key	WM11673-ND	1.81	1	$ 1.81
CONN 6POS DURA-CLIK 0.079"	P4	Molex	560020-0620	Digi-Key	WM10866CT-ND	1.64	1	$ 1.64
MOSFET N-CH 30V 8.7A 2.1W 6-PQFN (2x2)	Q1	Infineon	IRLHS6342TRPBF	Digi-Key	IRLHS6342TRPBFCT-ND	1.06	1	$ 1.06
RES 0.0 OHM 3/4W 1206	R1	Stackpole Electronics	HCJ1206ZT0R00	Digi-Key	HCJ1206ZT0R00CT-ND	0.72	1	$ 0.72
RES 4.7K OHM 1% 1/10W 0603	R2	Yageo	RC0603FR-074K7L	Digi-Key	311-4.70KHRCT-ND	0.13	1	$ 0.13
RES 22.1 OHM 1% 1/10W 0603	R3	Yageo	RC0603FR-0722R1L	Digi-Key	311-22.1HRCT-ND	0.13	1	$ 0.13
RES 10K OHM 1% 1/10W 0603	R4	Yageo	RC0603FR-0710KL	Digi-Key	311-10.0KHRCT-ND	0.13	1	$ 0.13
RES 604 OHM 1% 1/10W 0603	R5	Yageo	RC0603FR-07604RL	Digi-Key	311-604HRCT-ND	0.13	1	$ 0.13
RES 3.3K OHM 1% 1/4W 0603	R6	Panasonic	ERJPA3F3301V	Digi-Key	P3.3KBYCT-ND	0.21	1	$ 0.21
RES 3.3K OHM 1% 1/4W 0603	R7	Panasonic	ERJPA3F3301V	Digi-Key	P3.3KBYCT-ND	0.21	1	$ 0.21
RES 120 OHM 1% 1/10W 0603	R8	Yageo	RC0603FR-07120RL	Digi-Key	311-120HRCT-ND	0.13	1	$ 0.13
RES 604 OHM 1% 1/10W 0603	R9	Yageo	RC0603FR-07604RL	Digi-Key	311-604HRCT-ND	0.13	1	$ 0.13
RES 120 OHM 1% 1/10W 0603	R10	Yageo	RC0603FR-07120RL	Digi-Key	311-120HRCT-ND	0.13	1	$ 0.13
RES 604 OHM 1% 1/10W 0603	R11	Yageo	RC0603FR-07604RL	Digi-Key	311-604HRCT-ND	0.13	1	$ 0.13
RES 604 OHM 1% 1/10W 0603	R12	Yageo	RC0603FR-07604RL	Digi-Key	311-604HRCT-ND	0.13	1	$ 0.13
RES 0.0 OHM 3/4W 1206	R13	Stackpole Electronics	HCJ1206ZT0R00	Digi-Key	HCJ1206ZT0R00CT-ND	0.72	1	$ 0.72
RES 10K OHM 1% 1/10W 0603	R14	Yageo	RC0603FR-0710KL	Digi-Key	311-10.0KHRCT-ND	0.13	1	$ 0.13
RES 10K OHM 1% 1/10W 0603	R15	Yageo	RC0603FR-0710KL	Digi-Key	311-10.0KHRCT-ND	0.13	1	$ 0.13
RES 4.7K OHM 1% 1/10W 0603	R16	Yageo	RC0603FR-074K7L	Digi-Key	311-4.70KHRCT-ND	0.13	1	$ 0.13
RES 4.7K OHM 1% 1/10W 0603	R17	Yageo	RC0603FR-074K7L	Digi-Key	311-4.70KHRCT-ND	0.13	1	$ 0.13
RES 100 OHM 1% 1/10W 0603	R18	Yageo	RC0603FR-07100RL	Digi-Key	311-100HRCT-ND	0.13	1	$ 0.13
RES 510 OHM 5% 1/10W 0603	R19	Yageo	RC0603JR-07510RL	Digi-Key	311-510GRCT-ND	0.13	1	$ 0.13
SW SPST 2POS DIP 0.1A 20V	S1	CTS	219-2MST	Digi-Key	CT2192MST-ND	0.79	1	$ 0.79
Thru Test Point	TH_TP1							
Thru Test Point	TH_TP2							
Thru Test Point	TH_TP3							
IC CURRENT SENSOR HALL EFFECT 8-SOIC	U1	Allegro MicroSystems	ACS722LLCTR-10AU-T	Digi-Key	620-1636-1-ND	7.26	1	$ 7.26
IC DIFFERENTIAL I2C BUFFER PCA9615	U2	NXP Semiconductors	PCA9615DPJ	Digi-Key	568-11484-1-ND	3.87	1	$ 3.87
IC ADC 12-BIT VSSOP-10	U3	Texas Instruments	ADS1015IDGSR	Digi-Key	296-41185-1-ND	3.62	1	$ 3.62
IC REG LDO 3V 0.2A 4-TDFN	U4	Microchip	MIC94310-PYMT-TR	Digi-Key	576-4761-1-ND	0.38	1	$ 0.38
							Total:	$ 76.33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HV HIGH
P2
CAUTION HV
HV LOW
HV CURRENT SENSE
R13
R1
U1
3V3
C7
12V
MODE SELECT
1 0
S1
CURRENT SENSE OUT
P3
K1
R14
R15
D1
C1
Q1
R3
GND
R2
LED1
C2
P1
C5
C6
C4
C3
R4
SOLAR RELAY
D2
SOLAR RELAY GND
R6
R9
R12
U2
R7
R5
R11
R10
DSDAN
DSDAP
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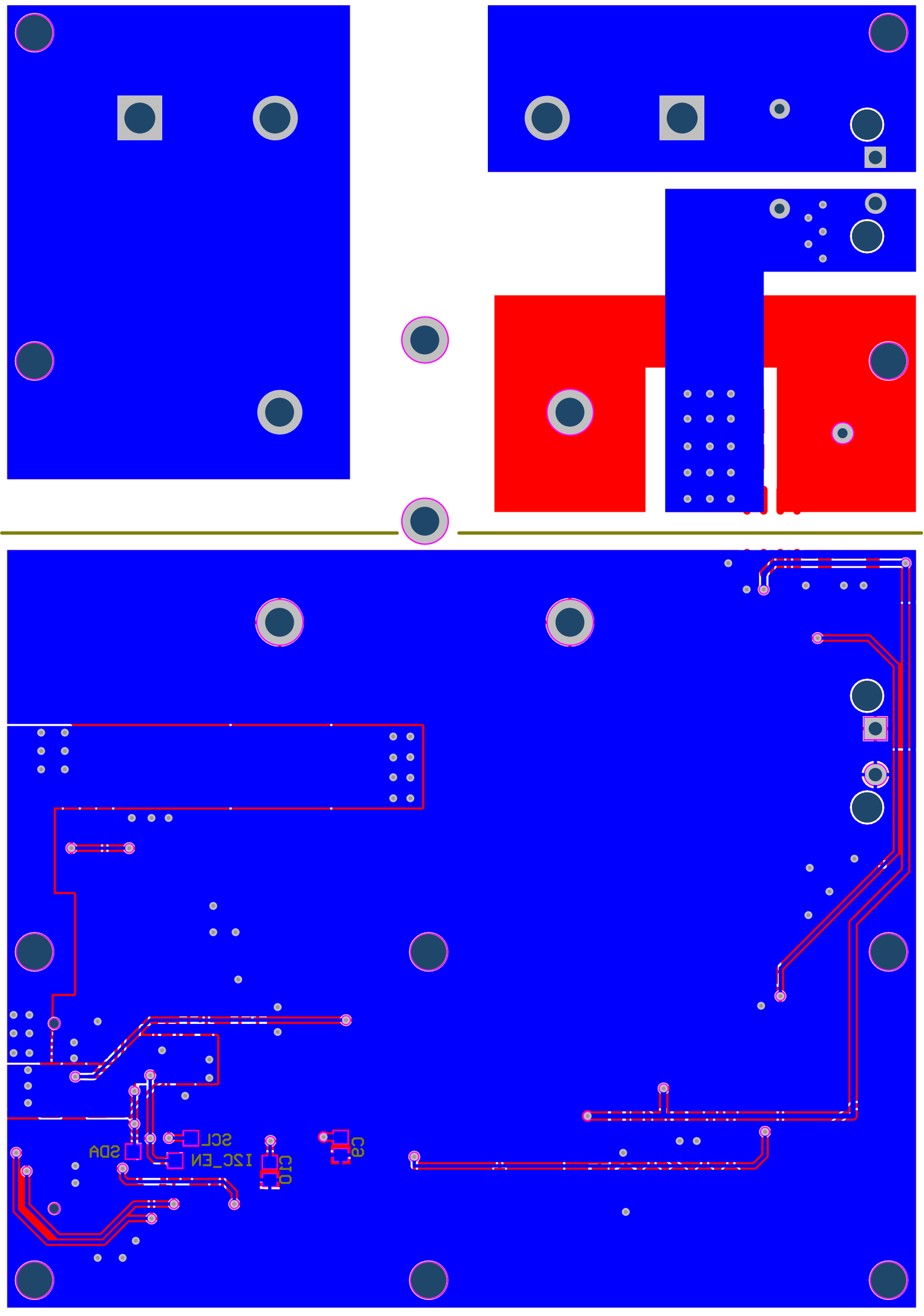
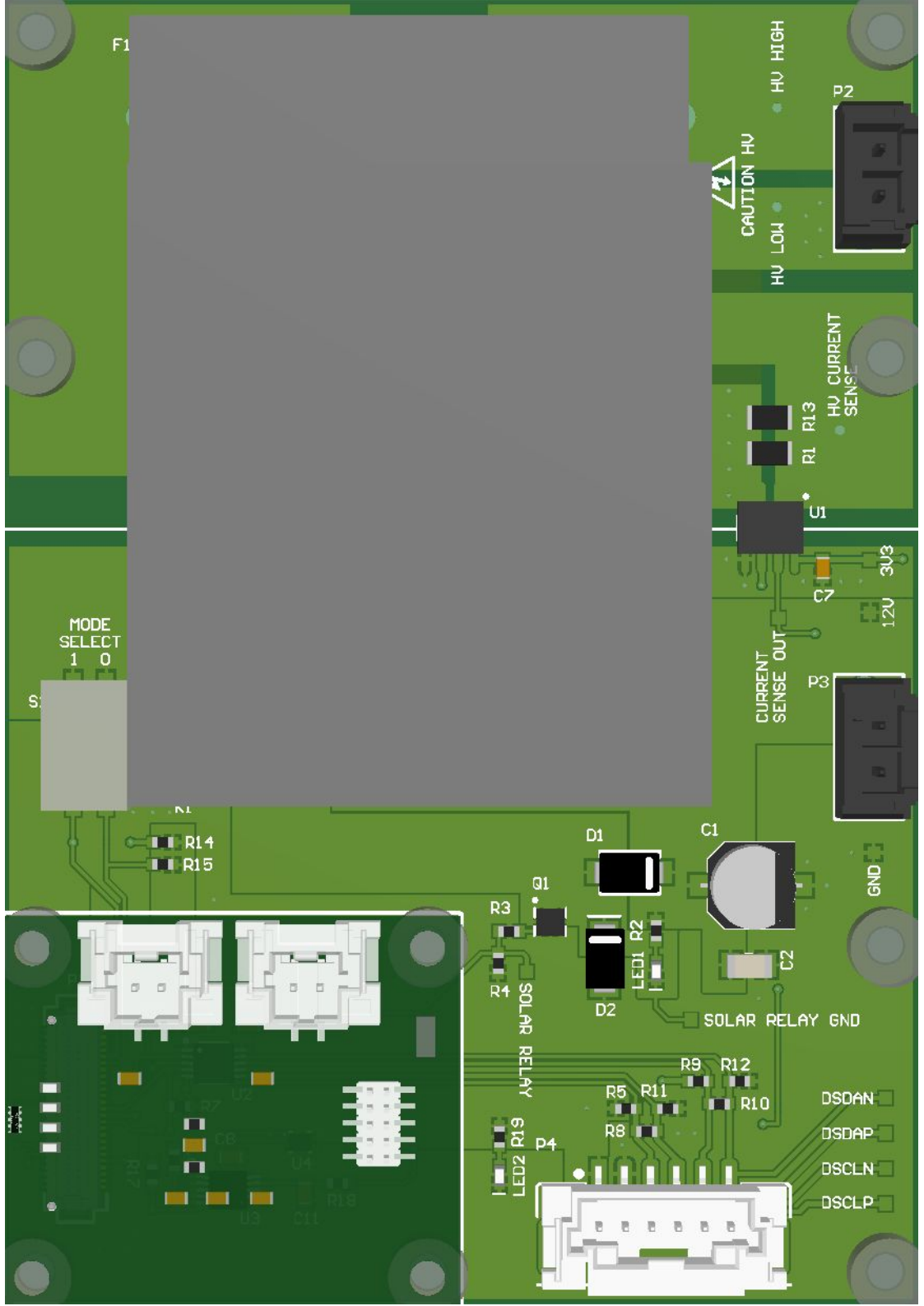
C8
R16
R17
U4
R19
P4
R8
LED2
U3
C11
R18


SCL
SDA
I2C_EN
C1
C2


F1
HV HIGH
P2
CAUTION HV
HV LOW
HV CURRENT SENSE
R13
R1
U1
3V3
C7
12V
MODE SELECT
1 0
CURRENT SENSE OUT
P3
R14
R15
D1
C1
GND
Q1
R3
R2
LED1
R4
D2
C2
SOLAR RELAY
SOLAR RELAY GND
R9
R12
R5
R11
R10
R8
DSDAN
DSDAP
DSCLN
DSCLP
R19
LED2
P4

Electrical Rules Check Report

Class	Document	Message
		Successful Compile for MSXII_SolarSenseMaster.PrjPcb

Design Rules Verification Report

Filename : C:\Users\peiliang.guo\uw-midsun\hardware\MSXII_SolarSenseMaster\SolarSense

Warnings 0
Rule Violations 66

Warnings	
Total	0

Rule Violations	
Clearance Constraint (Gap=0.152mm) (All),(All)	0
Short-Circuit Constraint (Allowed=No) (All),(All)	0
Un-Routed Net Constraint ((All))	0
Modified Polygon (Allow modified: No), (Allow shelved: No)	0
Width Constraint (Min=0.254mm) (Max=0.4mm) (Preferred=0.4mm) (InNet('3V3'))	0
Width Constraint (Min=0.152mm) (Max=2.54mm) (Preferred=0.254mm) (All)	0
Power Plane Connect Rule(Relief Connect)(Expansion=0.508mm) (Conductor Width=0.254mm) (Air Gap=0.254mm)	0
Minimum Annular Ring (Minimum=0.15mm) (All)	0
Hole Size Constraint (Min=0.3mm) (Max=6.3mm) (All)	0
Hole To Hole Clearance (Gap=0.254mm) (All),(All)	0
Minimum Solder Mask Sliver (Gap=0.3mm) (All),(All)	36
Silk To Solder Mask (Clearance=0.178mm) (IsPad),(All)	22
Silk to Silk (Clearance=0.254mm) (All),(All)	0
Net Antennae (Tolerance=0mm) (All)	0
Board Clearance Constraint (Gap=0mm) (All)	8
Height Constraint (Min=0mm) (Max=70mm) (Prefered=12.7mm) (InComponent('K1') OR InComponent('K2'))	0
Height Constraint (Min=0mm) (Max=25.4mm) (Prefered=12.7mm) (All)	0
Total	66

Minimum Solder Mask Sliver (Gap=0.3mm) (All),(All)
Minimum Solder Mask Sliver Constraint: (0.298mm < 0.3mm) Between Pad C10-1(20.4mm,11.475mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.298mm < 0.3mm) Between Pad C11-1(23.1mm,9.275mm) on Top Layer And Pad C11-2(23.1mm,7.925mm) on
Minimum Solder Mask Sliver Constraint: (0.298mm < 0.3mm) Between Pad C3-1(18.125mm,21.469mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.298mm < 0.3mm) Between Pad C4-1(18.125mm,23.274mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.298mm < 0.3mm) Between Pad C5-1(14.225mm,23.274mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.298mm < 0.3mm) Between Pad C6-1(14.225mm,21.469mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.298mm < 0.3mm) Between Pad C7-1(62.664mm,57.075mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.298mm < 0.3mm) Between Pad C8-1(16.725mm,11.329mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.298mm < 0.3mm) Between Pad C9-1(25.8mm,13.375mm) on Bottom Layer And Pad C9-2(25.8mm,12.025mm)
Minimum Solder Mask Sliver Constraint: (0.105mm < 0.3mm) Between Pad P1-(4mm,22.05mm) on Multi-Layer And Pad P1-(5.5mm,22.8mm) on Top Layer
Minimum Solder Mask Sliver Constraint: (0.105mm < 0.3mm) Between Pad P1-(4mm,7.95mm) on Multi-Layer And Pad P1-(5.5mm,7.2mm) on Top Layer
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.3mm) Between Pad Q1-1(40.875mm,29.95mm) on Top Layer And Pad Q1-2(40.875mm,29.3mm) on
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.3mm) Between Pad Q1-2(40.875mm,29.3mm) on Top Layer And Pad Q1-3(40.875mm,28.65mm) on
Minimum Solder Mask Sliver Constraint: (0.275mm < 0.3mm) Between Pad Q1-2(40.875mm,29.3mm) on Top Layer And Pad Q1-8(41.8mm,28.56mm) on
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.3mm) Between Pad Q1-3(40.875mm,28.65mm) on Top Layer And Pad Q1-7(41.8mm,29.6mm) on
Minimum Solder Mask Sliver Constraint: (0.202mm < 0.3mm) Between Pad Q1-3(40.875mm,28.65mm) on Top Layer And Pad Q1-8(41.8mm,28.56mm) on
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.3mm) Between Pad Q1-4(42.725mm,28.65mm) on Top Layer And Pad Q1-5(42.725mm,29.3mm) on
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.3mm) Between Pad Q1-4(42.725mm,28.65mm) on Top Layer And Pad Q1-7(41.8mm,29.6mm) on
Minimum Solder Mask Sliver Constraint: (0.202mm < 0.3mm) Between Pad Q1-4(42.725mm,28.65mm) on Top Layer And Pad Q1-8(41.8mm,28.56mm) on
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.3mm) Between Pad Q1-5(42.725mm,29.3mm) on Top Layer And Pad Q1-6(42.725mm,29.95mm) on
Minimum Solder Mask Sliver Constraint: (0.275mm < 0.3mm) Between Pad Q1-5(42.725mm,29.3mm) on Top Layer And Pad Q1-8(41.8mm,28.56mm) on
Minimum Solder Mask Sliver Constraint: (0.187mm < 0.3mm) Between Pad Q1-7(41.8mm,29.6mm) on Top Layer And Pad Q1-8(41.8mm,28.56mm) on Top
Minimum Solder Mask Sliver Constraint: (0.017mm < 0.3mm) Between Pad U2-1(13.96mm,19.5mm) on Top Layer And Pad U2-2(13.96mm,19mm) on Top
Minimum Solder Mask Sliver Constraint: (0.017mm < 0.3mm) Between Pad U2-10(18.24mm,19.5mm) on Top Layer And Pad U2-9(18.24mm,19mm) on Top
Minimum Solder Mask Sliver Constraint: (0.017mm < 0.3mm) Between Pad U2-2(13.96mm,19mm) on Top Layer And Pad U2-3(13.96mm,18.5mm) on Top
Minimum Solder Mask Sliver Constraint: (0.017mm < 0.3mm) Between Pad U2-3(13.96mm,18.5mm) on Top Layer And Pad U2-4(13.96mm,18mm) on Top
Minimum Solder Mask Sliver Constraint: (0.017mm < 0.3mm) Between Pad U2-4(13.96mm,18mm) on Top Layer And Pad U2-5(13.96mm,17.5mm) on Top
Minimum Solder Mask Sliver Constraint: (0.017mm < 0.3mm) Between Pad U2-6(18.24mm,17.5mm) on Top Layer And Pad U2-7(18.24mm,18mm) on Top
Minimum Solder Mask Sliver Constraint: (0.017mm < 0.3mm) Between Pad U2-7(18.24mm,18mm) on Top Layer And Pad U2-8(18.24mm,18.5mm) on Top
Minimum Solder Mask Sliver Constraint: (0.017mm < 0.3mm) Between Pad U2-8(18.24mm,18.5mm) on Top Layer And Pad U2-9(18.24mm,19mm) on Top
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.3mm) Between Pad U4-1(22.014mm,12.75mm) on Top Layer And Pad U4-2(22.014mm,12.15mm)
Minimum Solder Mask Sliver Constraint: (0.012mm < 0.3mm) Between Pad U4-1(22.014mm,12.75mm) on Top Layer And Pad U4-5(22.729mm,12.45mm)
Minimum Solder Mask Sliver Constraint: (0.012mm < 0.3mm) Between Pad U4-2(22.014mm,12.15mm) on Top Layer And Pad U4-5(22.729mm,12.45mm)
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.3mm) Between Pad U4-3(23.454mm,12.15mm) on Top Layer And Pad U4-4(23.454mm,12.75mm)
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.3mm) Between Pad U4-3(23.454mm,12.15mm) on Top Layer And Pad U4-5(22.729mm,12.45mm)
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.3mm) Between Pad U4-4(23.454mm,12.75mm) on Top Layer And Pad U4-5(22.729mm,12.45mm)

Silk To Solder Mask (Clearance=0.178mm) (IsPad),(All)
Silk To Solder Mask Clearance Constraint: (0.166mm < 0.178mm) Between Pad D1-1(45.869mm,33.1mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.166mm < 0.178mm) Between Pad D1-1(45.869mm,33.1mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.166mm < 0.178mm) Between Pad D1-2(49.869mm,33.1mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.166mm < 0.178mm) Between Pad D1-2(49.869mm,33.1mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.05mm < 0.178mm) Between Pad Q1-1(40.875mm,29.95mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.112mm < 0.178mm) Between Pad Q1-2(40.875mm,29.3mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.112mm < 0.178mm) Between Pad Q1-2(40.875mm,29.3mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.05mm < 0.178mm) Between Pad Q1-3(40.875mm,28.65mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.05mm < 0.178mm) Between Pad Q1-4(42.725mm,28.65mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.112mm < 0.178mm) Between Pad Q1-5(42.725mm,29.3mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.112mm < 0.178mm) Between Pad Q1-5(42.725mm,29.3mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.05mm < 0.178mm) Between Pad Q1-6(42.725mm,29.95mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.175mm < 0.178mm) Between Pad U3-1(19.4mm,7.8mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.176mm < 0.178mm) Between Pad U3-10(15mm,7.8mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.176mm < 0.178mm) Between Pad U3-2(19.4mm,8.3mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.176mm < 0.178mm) Between Pad U3-3(19.4mm,8.8mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.176mm < 0.178mm) Between Pad U3-4(19.4mm,9.3mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.176mm < 0.178mm) Between Pad U3-5(19.4mm,9.8mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.176mm < 0.178mm) Between Pad U3-6(15mm,9.8mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.176mm < 0.178mm) Between Pad U3-7(15mm,9.3mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.176mm < 0.178mm) Between Pad U3-8(15mm,8.8mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.176mm < 0.178mm) Between Pad U3-9(15mm,8.3mm) on Top Layer And Track

Board Clearance Constraint (Gap=0mm) (All)
Board Outline Clearance(Outline Edge): (Collision < 0.406mm) Between Board Edge And Track (0mm,0mm)(0mm,30mm) on Top Overlay
Board Outline Clearance(Outline Edge): (Collision < 0.406mm) Between Board Edge And Track (0mm,0mm)(35mm,0mm) on Top Overlay
Board Outline Clearance(Outline Edge): (Collision < 0.406mm) Between Board Edge And Track (0mm,30mm)(35mm,30mm) on Top Overlay
Board Outline Clearance(Outline Edge): (Collision < 0.406mm) Between Board Edge And Track (0mm,59.4mm)(30.1mm,59.4mm) on Bottom Overlay
Board Outline Clearance(Outline Edge): (Collision < 0.406mm) Between Board Edge And Track (0mm,59.4mm)(30.1mm,59.4mm) on Top Overlay
Board Outline Clearance(Outline Edge): (Collision < 0.406mm) Between Board Edge And Track (34.8mm,59.4mm)(70mm,59.4mm) on Bottom Overlay
Board Outline Clearance(Outline Edge): (Collision < 0.406mm) Between Board Edge And Track (34.8mm,59.4mm)(70mm,59.4mm) on Top Overlay
Board Outline Clearance(Outline Edge): (Collision < 0.406mm) Between Board Edge And Track (35mm,0mm)(35mm,30mm) on Top Overlay